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Altana Electrical Insulation GmbH

Abstract:

The present invention relates to coating compositions for flat assemblies, hybrids, SMD assemblies, comprising at least one binder or binder mixtures which are curable at 60°C-120°C, preferably at 70°C-110°C, more particularly at 80°C-90°C, and also to a process for preparing them and to their use for flat assemblies in electronics, hybrids, SMD assemblies and assembled printed circuit boards.